

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	MULTI-STAGED HEATING SYSTEM FOR FABRICATING MICROELECTRONIC DEVICES						
Application Number :	10/624397						
Confirmation Number:	6816						
First Named Applicant:	Igor Ivanov						
Attorney Docket Number:	5866-00400						
Art Unit:							
Examiner:							
Search string:	(6875691).pn						

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6875691	2005-04-05	Li et al.			

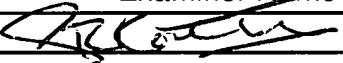
Signature

Examiner Name	Date
	7/30/06

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Examiner:							
Search string:	(20030235983).pn						
US Published Applications							
Note: Applicant is not required to submit a paper copy of cited US Published Applications							
init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20030235983	2003-12-25	Li et al.			
Signature							
Examiner Name				Date			
				4/30/06			

OCT 31 2003

Page 1 of 1

Form PTO-1449 (modified) List of Patents and Publications For Applicant's Information Disclosure Statement (Use several sheets if necessary)			CITY. DKT. NO. 5866-00400 APPLICANT: Ivanov et al. FILING DATE: July 22, 2003			SERIAL NO. 10/624,397 GROUP: Unknown		
U.S. PATENT DOCUMENTS								
EXAM. INITIALS	REF. DES.	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE	
<i>GRK</i>	A1	5830805	11/1998	Shacham-Diamond et al.	—	—	—	
<i>↓</i>	A2	6322677	11/2001	Woodruff et al.	—	—	—	
FOREIGN PATENT DOCUMENTS								
EXAM. INITIALS	REF. DES.	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRANSLATION YES/NO	
<i>GRK</i>	A3	WO02/34962	5/2002	WO	—	—	<i>No</i>	
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)								
<i>GRK</i>	A4	Riedel, "Electroless Nickel Plating," 1991, p. 39.						
<i>↓</i>	A5	O'Sullivan et al., "Electrolessly deposited diffusion barriers for microelectronics," IBM Journal of Research and Development, Vol. 42, No. 5, 1998, 20 pages.						
<i>↓</i>	A6	Lopatin et al., "Selective Electroless CoWP Deposition onto Pd-Activated In-Laid Cu Lines," VMIC Conference, 1997, pp. 219-224.						
<i>↓</i>	A7	Shacham-Diamond et al., "High aspect ratio quarter-micron electroless copper integrated technology," Microelectronic Engineering 37/38, 1997, pp. 77-88.						
<i>↓</i>	A8	Lantasov et al., "New plating bath for electroless copper deposition on sputtered barrier layers," Microelectronic Engineering 50, 2000, pp. 441-447.						

EXAMINER:

DATE CONSIDERED:

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the patent owner.

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